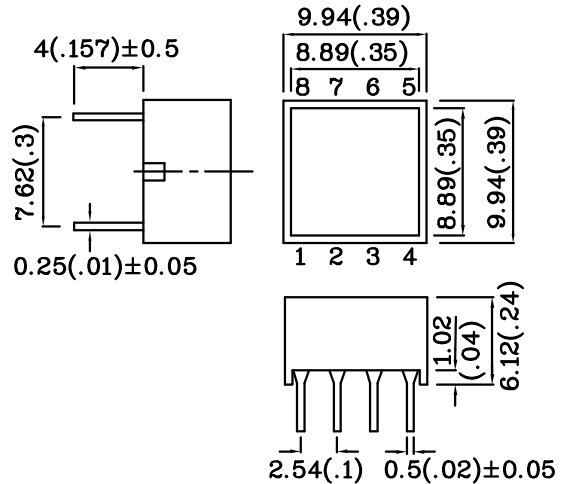
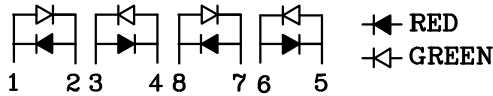


### Features

- UNIFORM LIGHT EMITTING AREA.
- LOW CURRENT OPERATION.
- EASILY MOUNTED ON P.C. BOARDS.
- FLUSH MOUNTABLE.
- EXCELLENT ON/OFF CONTRAST.
- CAN BE USED WITH PANELS AND LEGEND MOUNTS.
- RoHS COMPLIANT.



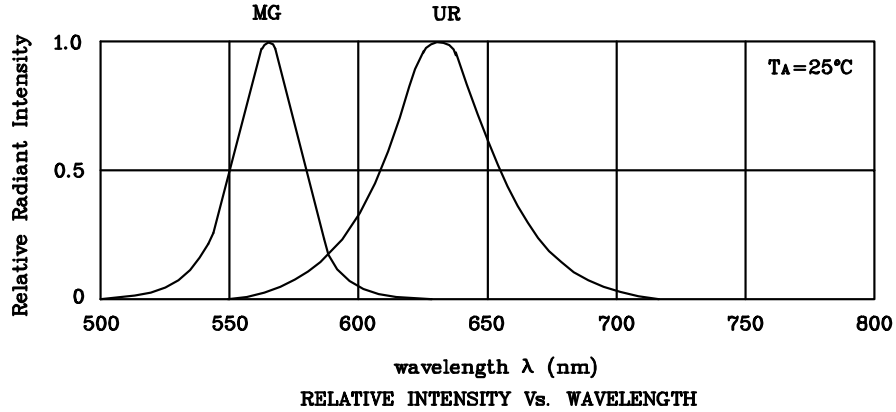
### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.

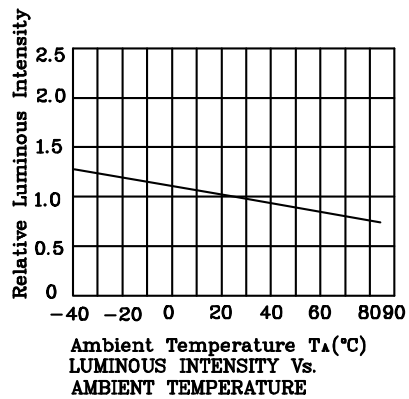
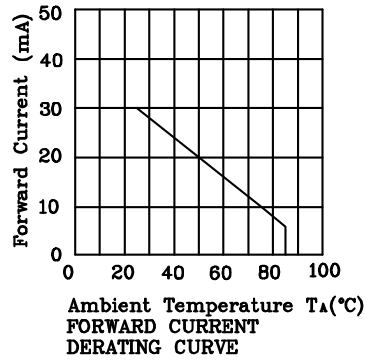
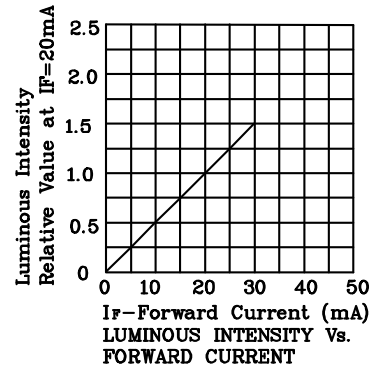
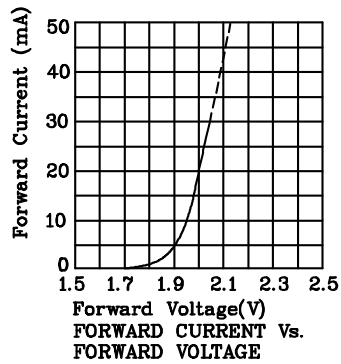
| Absolute Maximum Ratings<br>( $T_A=25^\circ\text{C}$ )         |                     | UR<br>(GaAsP/<br>GaP) | MG<br>(GaP) | Unit |
|----------------------------------------------------------------|---------------------|-----------------------|-------------|------|
| Reverse Voltage                                                | $V_R$               | 5                     | 5           | V    |
| Forward Current                                                | $I_F$               | 30                    | 25          | mA   |
| Forward Current (Peak)<br>1/10 Duty Cycle<br>0.1ms Pulse Width | $i_{FS}$            | 160                   | 140         | mA   |
| Power Dissipation                                              | $P_T$               | 105                   | 105         | mW   |
| Operating Temperature                                          | $T_A$               | -40 ~ +85             |             | °C   |
| Storage Temperature                                            | $T_{stg}$           | -40 ~ +85             |             |      |
| Lead Solder Temperature<br>[2mm Below Package Base]            | 260°C For 5 Seconds |                       |             |      |

| Operating Characteristics<br>( $T_A=25^\circ\text{C}$ )              |                 | UR<br>(GaAsP/<br>GaP) | MG<br>(GaP) | Unit          |
|----------------------------------------------------------------------|-----------------|-----------------------|-------------|---------------|
| Forward Voltage (Typ.)<br>( $I_F=20\text{mA}$ )                      | $V_F$           | 2.0                   | 2.2         | V             |
| Forward Voltage (Max.)<br>( $I_F=20\text{mA}$ )                      | $V_F$           | 2.5                   | 2.5         | V             |
| Reverse Current<br>( $V_R=5\text{V}$ )                               | $I_R$           | 10                    | 10          | $\mu\text{A}$ |
| Wavelength of Peak<br>Emission ( $I_F=20\text{mA}$ )                 | $\lambda_P$     | 627                   | 565         | nm            |
| Wavelength of Dominant<br>Emission ( $I_F=20\text{mA}$ )             | $\lambda_D$     | 625                   | 568         | nm            |
| Spectral Line Full Width<br>At Half-Maximum<br>( $I_F=20\text{mA}$ ) | $\Delta\lambda$ | 45                    | 30          | nm            |
| Capacitance<br>( $V_F=0\text{V}$ , $f=1\text{MHz}$ )                 | $C$             | 15                    | 15          | pF            |

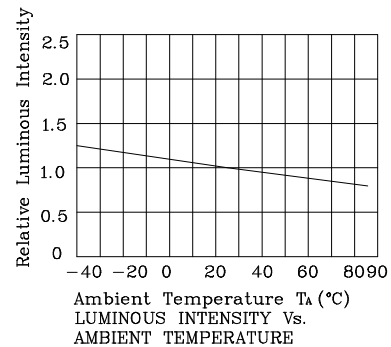
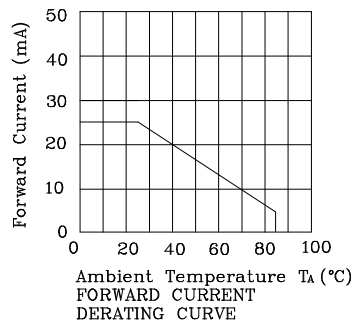
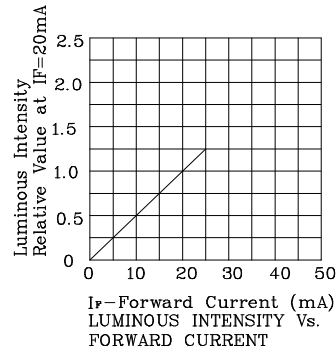
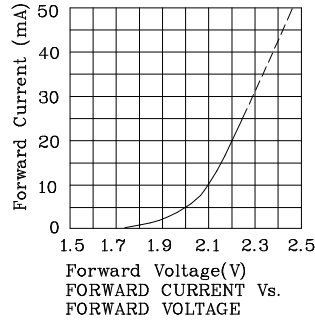
| Part Number | Emitting Color | Emitting Material | Lens-color     | Luminous Intensity<br>( $I_F=20\text{mA}$ )<br>mcd |      | Wavelength<br>nm<br>$\lambda_P$ |
|-------------|----------------|-------------------|----------------|----------------------------------------------------|------|---------------------------------|
|             |                |                   |                | min.                                               | typ. |                                 |
| XEURMG2965M | Red            | GaAsP/GaP         | White Diffused | 10                                                 | 44   | 627                             |
|             | Green          | GaP               |                | 18                                                 | 65   | 565                             |



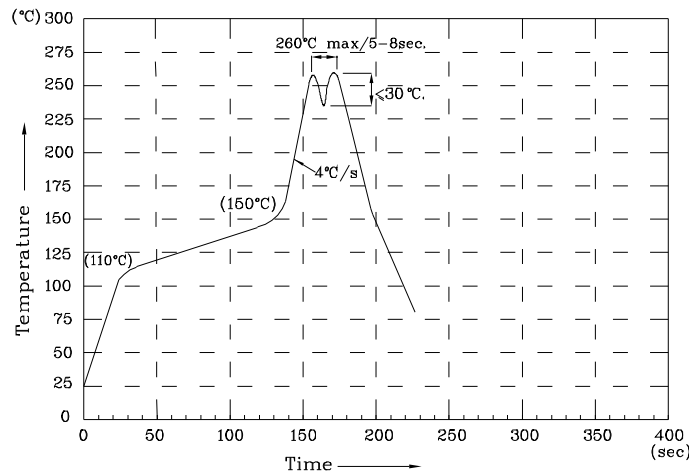
❖ UR



❖ MG



Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.